



Material Composition Sheet

Product: GS1508-CTAE3
 Package Type: SOIC-8 taped (250/reel)
 Manufacturer: Gennum Corporation

Date: 16-Jan-2007

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		1.13	Al	0.01	0.88	8850
			Si	1.12	99.11	991150
			Sub-total:	1.13	99.99	1000000
Die Attach	CRM1076R	0.15	Ag	0.11	73.33	733333
			Epoxy Resin	0.04	26.66	266667
			Sub-total:	0.15	99.99	1000000
Lead Finish External		1.33	Sn	1.33	100.00	1000000
			Sub-total:	1.33	100.00	1000000
Lead Finish Internal		0.19	Ag	0.19	100.00	1000000
			Sub-total:	0.19	100.00	1000000
Leadframe	Olin 194FH	24.26	Cu	23.65	97.48	974856
			Fe	0.57	2.34	23495
			P	0.01	0.04	412
			Zn	0.03	0.12	1237
			Sub-total:	24.26	99.98	1000000
Marking Ink	Wieder W238	0.00		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G600	48.62	Carbon Black	0.15	0.30	3085
			Epoxy Cresol Novolac	1.94	3.99	39901
			Epoxy Resin	2.77	5.69	56972
			Phenol Resin	2.43	4.99	49979
			SiO2	41.33	85.00	850062
			Sub-total:	48.62	99.97	999999
Wires	SGA3	0.21	Au	0.21	100.00	1000000
			Sub-total:	0.21	100.00	1000000
Total:		75.89				

GENNUM CORPORATION

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